

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10535

REV: E1

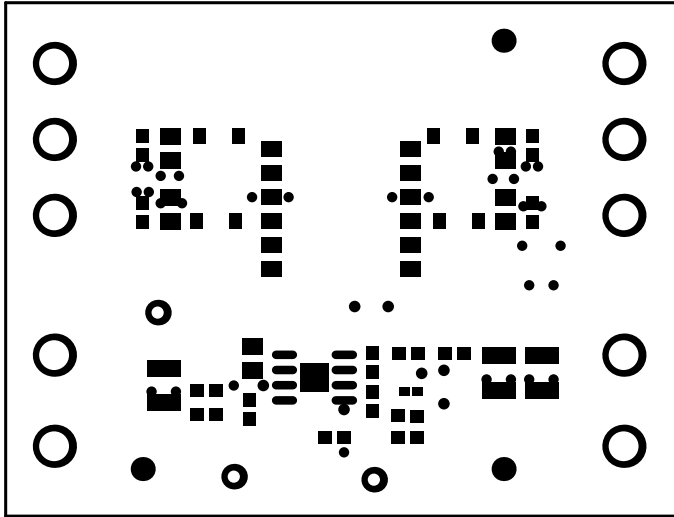
SUN REV: Not In VersionControl

LAYER NAME = Top Overlay

PLOT NAME = Top Overlay

GENERATED : 10/9/2014 11:08:56 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10535

REV: E1

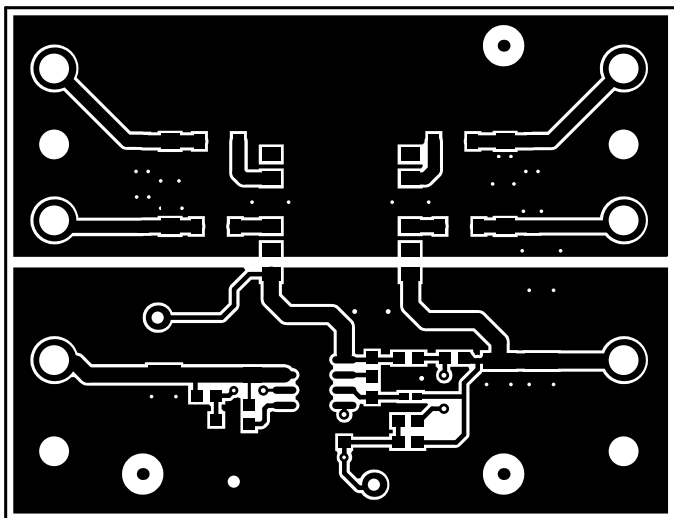
SUN REV: Not In VersionControl

LAYER NAME = Top Solder

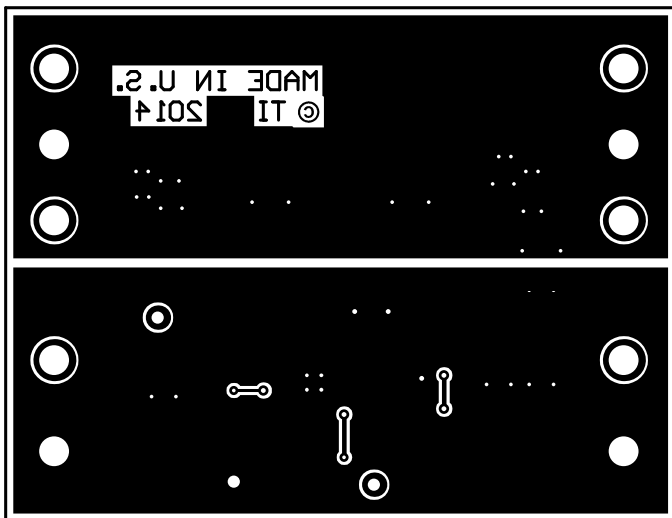
PLOT NAME = Top Solder Mask

GENERATED : 10/9/2014 11:08:57 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10535	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/9/2014 11:08:57 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10535

REV: E1

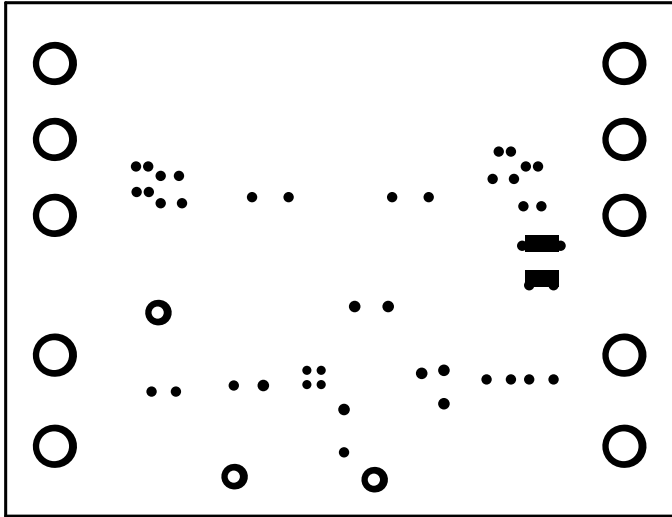
SUN REV: Not In VersionControl

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

GENERATED : 10/9/2014 11:08:58 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10535

REV: E1

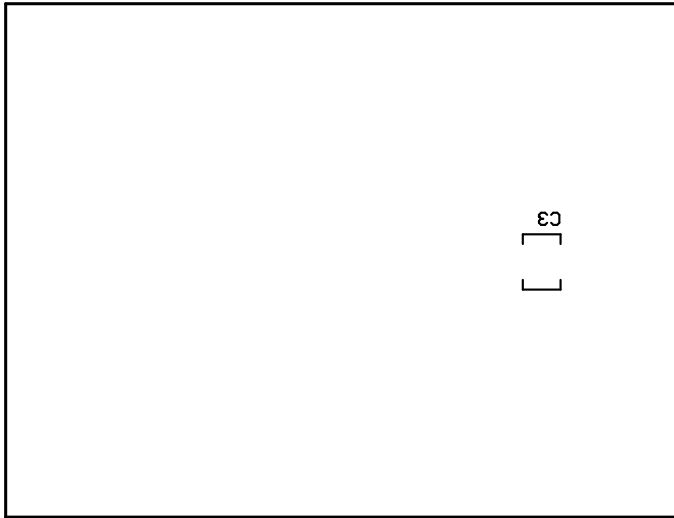
SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

PLOT NAME = Bottom Solder Mask

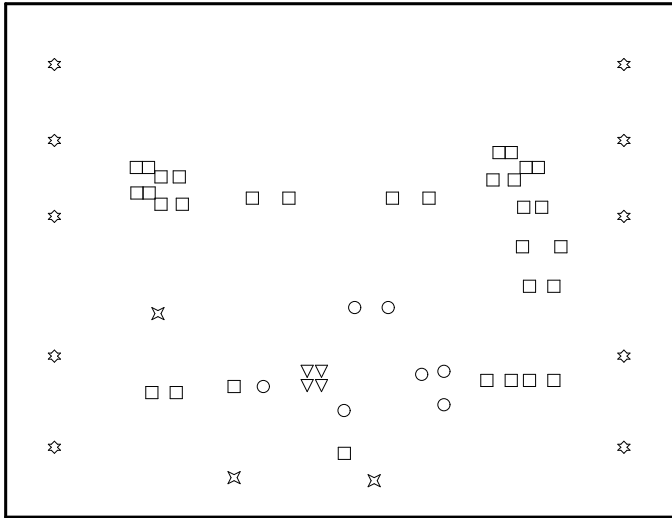
GENERATED : 10/9/2014 11:09:00 AM

TEXAS INSTRUMENTS



8 [ ]

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10535	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/9/2014 11:09:00 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10535

REV: E1

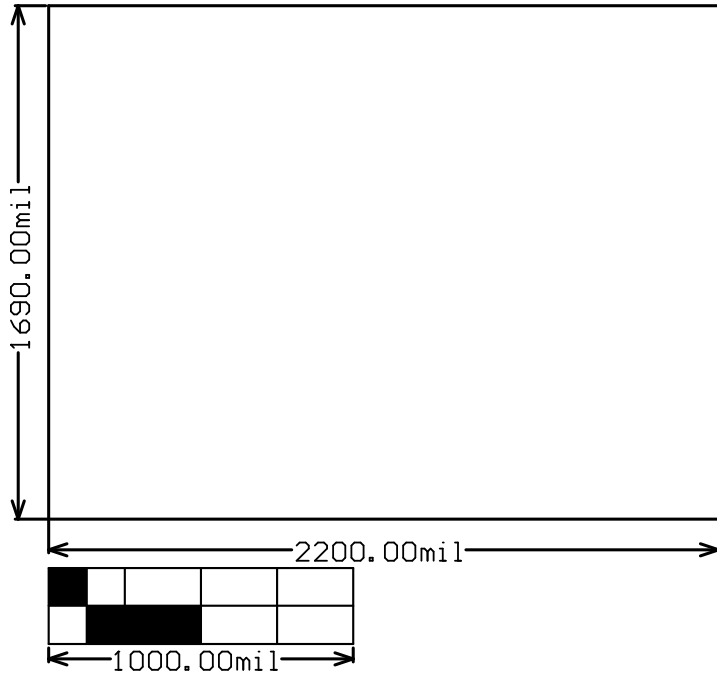
SUN REV: Not In VersionControl

LAYER NAME = Drill Drawing

PLOT NAME = Drill Drawing

GENERATED : 10/9/2014 11:09:01 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10535	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/9/2014 11:09:02 AM	TEXAS INSTRUMENTS	



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